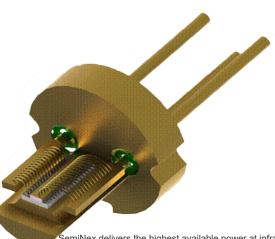
12/1/23, 7:13 AM PI Sheet

Preliminary Data Sheet





SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary we will further optimize the design of our InP laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.



TO-56 Packaged Laser Diode

High Power Single-Mode and Multi-Mode SemiNex Lasers

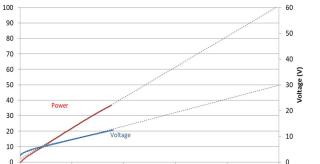
12xx to 19xx nm Custom Wavelengths Available Lensed Options Available

- Applications
 OEM Medical
- Professional Medical LiDAR
- Military / AerospaceIllumination

Features

Power (W)

- Cost effective High Output Power
- High Dynamic Range
- High Efficiency Standard Low Cost Package



40

Measured data with 100ns

Current (A)

100

Estimated data with 4ns pulse width

1550nm Triple Junction LIV

12/1/23, 7:13 AM PI Sheet

12/1/23, 7:13 AM PI Sheet



Triple Junction TO56



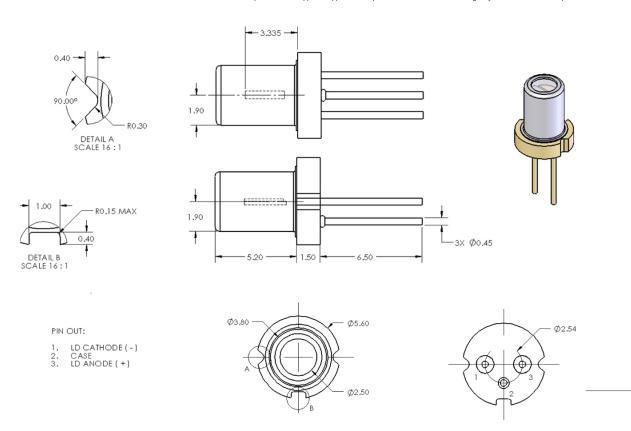
	Symbol	TO56-264	Units
Optical	-		
Vavelength	λ _c	1550	nm (±20)
Output Power (<10ns)	P∘	40.00	watts (±10%)
Output Power (150ns)	P∘	21.00	watts (±10%)
Cavity Length (typ.)	CL	2500	μm
No. of Junctions		3	
Emitter Width	W	50	μm
Emitter Height	Н	10	μm
Operating Current (<10ns)	I _{op}	40	A
Operating Current (150ns)	I _{op}	25	A
Operating Voltage	V_{op}	22	V
hreshold Current	I _{th}	0.4	Α
pecifications			
Spectral Width	δλ	22	nm 3dB
Fast Axis Div.	Θ_perp	28	deg FWHM
Slow Axis Div.	Θ_parallel	12	deg FWHM
Pulse Width	PW	150	ns
Outy Cycle	DC	0.1	%
Mechanical			
Veight	_	0.5	g
Operating Temp.**		-40 to 85	°C
Storage Temp.		-40 to 85	°C

Specified values are rated at a constant heat sink temperature of 20°C.

**Specified operating conditions are based on 20C heat sink temperature. High temperature operation will reduce performance and MTTF.

Unless otherwise indicated all values are nominal.

All TO56 products are capped. Capped TO56 specifications assume heatsinking only on flat surface where pins extend.



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Date Created: Dec 1 2023 1:11PM UTC